Emerging Technologies of Integral Image and 3D Display

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Message from the Guest Editors

3D imaging and display have been applied broadly to fields and industries in education, medical treatment, manufacturing, entertainment and securities, to name a few. This Special Issue will describe the recent developments and prospects for the emerging technologies in Integral Imaging and 3D display. Original research articles and reviews are welcome. Research areas may include, but need not limited to, the following:

- 3D sensing and imaging technologies;
- 3D visualization and display technologies;
- Algorithms for 3D information processing;
- Deep learning and artificial intelligence for 3D information processing;
- Augmented/Virtual Reality and wearable displays;
- Devices for 3D imaging and visualization;
- Holographic applications in 3D imaging and visualization;
- Novel materials for 3D sensing and display;
- Applications of integral imaging and 3D display in medical industries;
- Biomedical applications of 3D sensing and imaging;
- 3D object recognition and tracking.

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Special Issue

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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